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**FOR IMMEDIATE RELEASE**

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# Press Release

## **High Reliability & High Temperature Application Solution – Solder Joint Encapsulant Paste**

(Albany, NY) August 7, 2017 – Dr. Wusheng Yin, YINCAE Advanced Materials LLC, will be discussing a new technology – solder joint encapsulant paste for high temperature applications, at the 2017 SMTA International Conference in Rosemont, IL, as a potential solution to the current limitations and challenges presented by miniaturization. As miniaturization continues to be the driving force, the industry is beginning to face challenges associated with this trend including: warpage and reliability issues.

YINCAE has developed a solder joint encapsulant paste compatible with typical lead-free reflow profiles, but also has the ability to withstand high temperature applications (300°C). This paste also enhances solder joint strength, drop performance, and thermal cycling performance. As a result, using this paste can eliminate traditional underfill or corner bonding materials, as well as red glue, currently used for double sided reflow processes.

We welcome you to attend this speaker presentation and stop by our booth, 329, at SMTAI. Additional information regarding Dr. Yin’s speaking session is available by contacting YINCAE at [info@yincae.com](mailto:info@yincae.com).

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: [YINCAE Website](#).

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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